

BRS:
BRS:
Pending
Active
L2: (2) 09/944246
L3: ("6075284" "6117710" "6630728" "6060778").pn. "20030001285" "20040026773" ("6075284" "6117710" "6630728" "6060778").pn. "20030001285" "20040026773" ("6576494" "6501184" "6429528" "6339254" "6228687" "6084058" "6088920" "6066514" "5973393" "5866953" "5815000" "5138434" "5107328").pn.
L4: (1738404) insulat\$4 dielectric
L5: (13541) exposed adj2 contact
L6: (725257) covering
L7: (113) 4 with 5 with 6
L8: (27471208) (@ad @pd) < 20010718
L9: (80) 7 and 8
L10: (23186) chipsize chip adj size stack\$4 adj (chip package)
L11: (2) 9 and 10
Failed
Saved:
(2251450) (encapsula\$3 encapsulation mold\$3 resin)
(14073) stack\$4 near2 ((microchip micro adj chip chip integrated adj circuit die ic semic
(2460392) (offset stagger\$3 shift\$3 zigzag\$4 align\$4 near2 angle pitch oblique\$4 inclin\$4
(12434) (leadframe lead adj frame)0
(1218718) (leadframe lead adj frame lead)
(6841) (offset stagger\$3 shift\$3 zigzag\$4 align\$4 near2 angle pitch oblique\$4 inclin\$4
(79) ((leadframe lead adj frame)0
(444) ((leadframe lead adj frame)0
(18011) (offset stagger\$3 shift\$3 zigzag\$4 align\$4 near2 angle pitch oblique\$4 inclin\$4
(241) ((leadframe lead adj frame)0
(888) ((leadframe lead adj frame)0
(801) ((leadframe lead adj frame)0

Buttons: Browse Queue Clear

DBs: USPAT:US POPUB:EPO:JPO:DERWENT:IBM:TD8

Default operator: OR

Plurals

Highlight all hit terms initially

oct 2004

	U	Inventor	Document ID	Issue D/P	Title	Current O	Current X Ref	Retrieval C	S	C	P	J	Image	Doc. D	P
1	<input type="checkbox"/>	AKRAM, S et al.	US 6228687 B	200105:18	Fabrication of chip-scale package involves adhering pr				<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	US 6228687	<input checked="" type="checkbox"/>
2	<input type="checkbox"/>	AKRAM, S et al.	US 6088920 A	200007:16	Modular die socket for packaging semiconductor die, h				<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	US 6088920	<input checked="" type="checkbox"/>
3	<input type="checkbox"/>	AKRAM, S et al.	US 5868953 A	199902:14	Heat sink for semiconductor chip of BGA, PGA, TAB; S				<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	US 5868953	<input checked="" type="checkbox"/>
4	<input type="checkbox"/>	AKRAM, S et al.	JP 09197006 A	199707:14	Semiconductor die packing method - involves mounting				<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	US 5815000	<input checked="" type="checkbox"/>
5	<input type="checkbox"/>	AKRAM, S et al.	TW 303502 A	199704:11	Temporary semiconductor package having dense array				<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	US 6084058	<input checked="" type="checkbox"/>
6	<input type="checkbox"/>	Akram, Salman	US 6228687 B	200105:18	Wafer-level package and methods of fabricating	438/125	257/E21.508		<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	US 6228687	<input checked="" type="checkbox"/>
7	<input type="checkbox"/>	Akram, Salman	US 5868953 A	199902:14	Packaged die on PCB with heat sink encapsulant	257/790	257/887		<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	US 5868953	<input checked="" type="checkbox"/>
8	<input type="checkbox"/>	BROOKS, J M et al	US 6066514 A	200005:4	Enhancing adhesion of a semiconductor die for mold co				<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	US 6066514	<input checked="" type="checkbox"/>